

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Sang Hyun YI et al

Serial No.

Filed: January 4, 2002

For: SEMICONDUCTOR DEVICE HAVING NO CRACKS IN ONE OR MORE LAYERS UNDERLYING A METAL LINE LAYER AND METHOD OF MANUFACTURING THE SAME

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to initial examination on the merits, please amend the application identified above as follows:

IN THE DRAWINGS

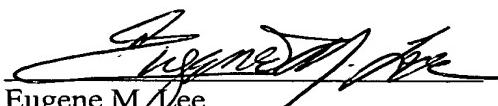
Kindly substitute the attached sheet "3/17" depicting Figures 3A and 3B for the sheet designated "3/17" appended to the application. Figure 3A, second occurrence on this sheet of drawing, has been corrected to read — — Fig. 3B — —.

REMARKS

This drawing amendment is presented to correct an obvious clerical error.

Respectfully submitted,

January 4, 2002
Date


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